

MATERIAL DECLARATION



NO	BREAKDOWN OF PART	MANUFACTURER	MATERIAL NAME	CHEMICAL SYMBOL	CAS NO.	%	TOTAL		1.8180	
							WEIGHT	SUBSTANCE MASS. (Mg)	%	SUBSTANCE %
1	Alumina Substrate	Leatec Fine Ceramics	Al2O3 substrate	Al2O3	1344-28-1	96.00	268.00	257.280	14.741	14.1518
				SiO2	14808-60-7	3.00		8.040		0.4422
				MgO	1309-48-4	1.00		2.680		0.1474
2	Resistor Layer	SUMITOMO	Resistive	Silver	744-22-4	30.00	60.00	18.000	3.300	0.9901
				Paste	744-05-3	10.00		6.000		0.3300
				Puthenium Oxide	12036-10-1	10.00		6.000		0.3300
				Lead Oxide	1317-36-8	15.00		9.000		0.4950
				Boron Trioxide	1303-86-2	2.00		1.200		0.0660
				Aluminium Oxide	1344-28-1	2.00		1.200		0.0660
				Silicon Dioxide	7631-86-9	10.00		6.000		0.3300
				Zinc Oxide	1314-13-2	2.00		1.200		0.0660
				Copper Oxide	1317-38-0	0.50		0.300		0.0165
				Manganese Oxide	1317-35-7	1.50		0.900		0.0495
				Tantalum Oxide	1314-61-0	1.50		0.900		0.0495
				Titanium Dioxide	13463-67-7	0.50		0.300		0.0165
Terpineol	8000-41-7	10.00	6.000	0.3300						
Dibutyl Decanedioate	109-43-3	5.00	3.000	0.1650						
3	Flange	HCT	Lead Frame	Cu	7440-50-8	100.00	128.00	128.000	7.041	7.0407
4	Solder	SHENMAO	Lead-free solder	Sn	7440-31-5	94.30	112.00	105.616	6.161	5.8095
				Ag	7440-22-4	3.00		3.360		0.1848
				Cu	7440-50-8	0.50		0.560		0.0308
				Rosin	8050-09-7	2.00		2.240		0.1232
				Activator	Not Established	0.10		0.112		0.0062
				Others	Not Established	0.10		0.112		0.0062
5	Molding	ETERNAL	Epoxy Resin	Crystalline Silica	14808-60-7	72.50	1250.00	906.250	68.757	49.8487
				Fused Silica	60676-86-0	10.00		125.000		6.8757
				Epoxy Resin	29690-82-2	10.00		125.000		6.8757
				Phenol Resin	9003-35-4	5.00		62.500		3.4378
				Metal hydroxide	-	2.00		25.000		1.3751
				Carbon Black	1333-86-4	0.50		6.250		0.3438

